



STPS1150/A

POWER SCHOTTKY RECTIFIER

MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	1 A
V_{RRM}	150 V
$T_j(\text{max})$	175°C
$V_F(\text{max})$	0.67 V

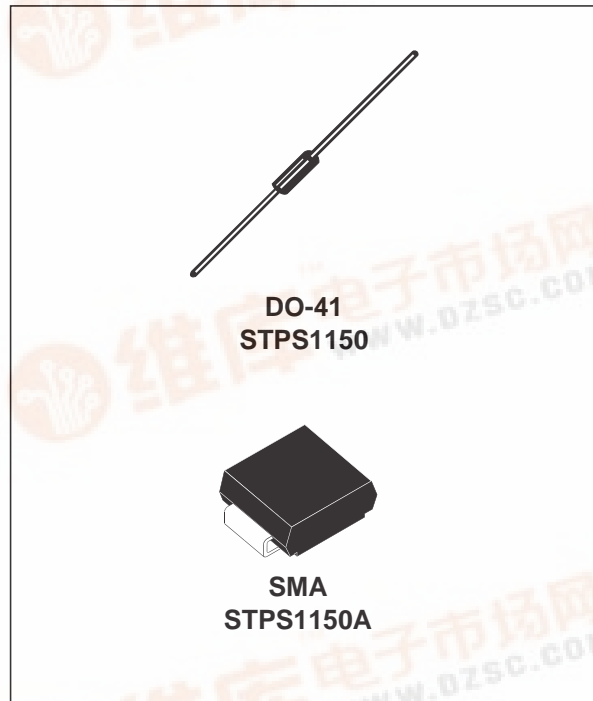
FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP FOR HIGHER EFFICIENCY AND EXTENDED BATTERY LIFE
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

DESCRIPTION

150V Power Schottky rectifier are suited for switch Mode Power Supplies on up to 24V rails and high frequency converters.

Packaged in SMA and Axial, this device is intended for use in consumer & computer applications like TV, STB, PC and DVD where low drop forward voltage in required to reduce power dissipation.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		150	V	
$I_{F(RMS)}$	RMS forward current		15	A	
$I_{F(AV)}$	Average forward current	$T_L = 160^\circ\text{C} \delta = 0.5$ SMA	1	A	
		$T_L = 150^\circ\text{C} \delta = 0.5$ DO-41			
I_{FSM}	Surge non repetitive forward current	Half wave, single phase, 50Hz	SMA	50	A
			DO-41	75	
P_{ARM}	Repetitive peak avalanche power	$t_p = 1\mu\text{s} \quad T_j = 25^\circ\text{C}$	1500	W	
T_{stg}	Storage temperature range		- 65 to + 150	°C	
T_j	Maximum junction temperature *		175	°C	
dV/dt	Critical rate of rise of reverse voltage (rated $V_R, T_j = 25^\circ\text{C}$)		10000	V/ μs	

* $\therefore \frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
$R_{th(j-l)}$	Junction to leads	Lead length = 10 mm	DO-41	30	°C/W
			SMA	20	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I_R^*	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = 150\text{V}$		0.2	1	μA
		$T_j = 125^\circ\text{C}$			0.2	1	mA
V_F^*	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 1\text{A}$		0.78	0.82	V
		$T_j = 125^\circ\text{C}$			0.62	0.67	
		$T_j = 25^\circ\text{C}$	$I_F = 2\text{A}$		0.85	0.89	
		$T_j = 125^\circ\text{C}$			0.69	0.75	

Pulse test : * $t_p \leq 250 \mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation:

$$P = 0.59 \times I_{F(AV)} + 0.08 \times I_F^2(RMS)$$

Fig. 1: Conduction losses versus average current.

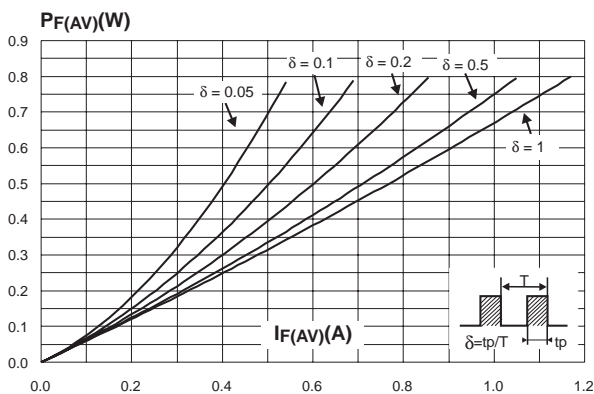


Fig. 3: Normalized avalanche power derating versus pulse duration.

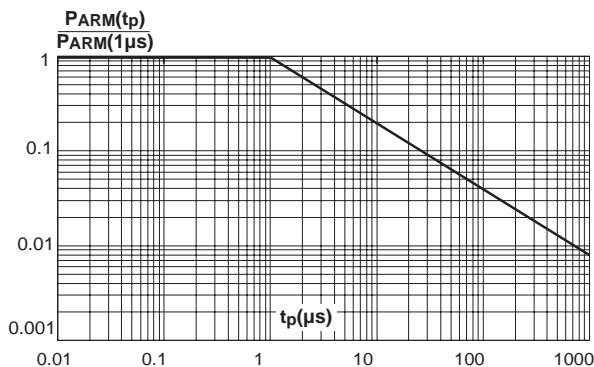


Fig. 2: Average forward current versus ambient temperature ($\delta = 0.5$).

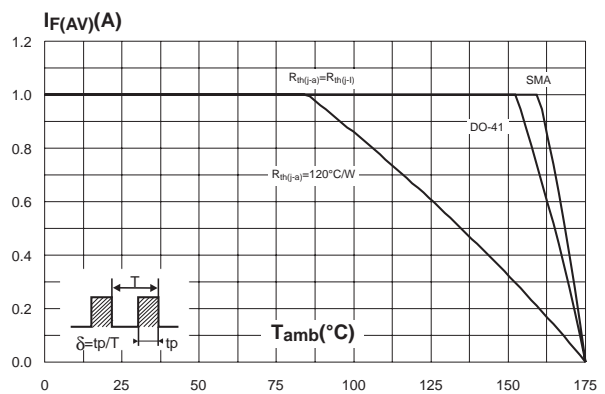


Fig. 4: Normalized avalanche power derating versus junction temperature.

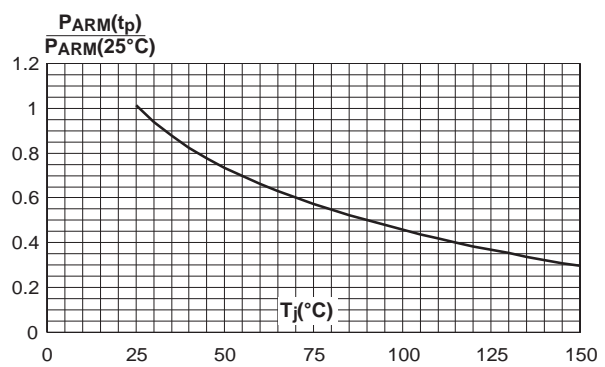


Fig. 5-1: Non repetitive surge peak forward current versus overload duration (maximum values) (SMA).

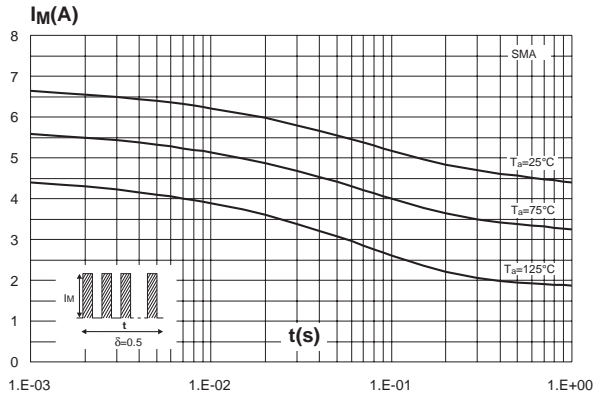


Fig. 5-2: Non repetitive surge peak forward current versus overload duration (maximum values) (DO-41).

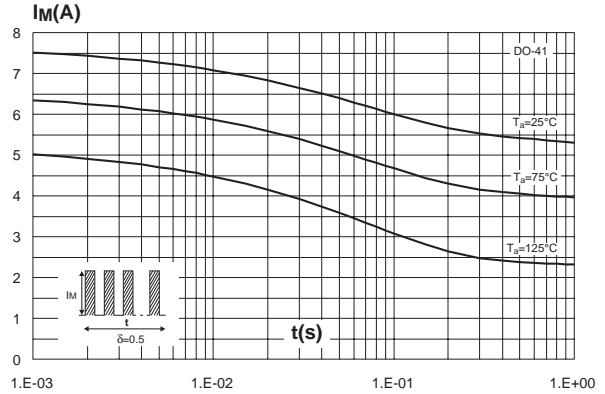


Fig. 6-1: Relative variation of thermal impedance junction to ambient versus pulse duration (SMA).

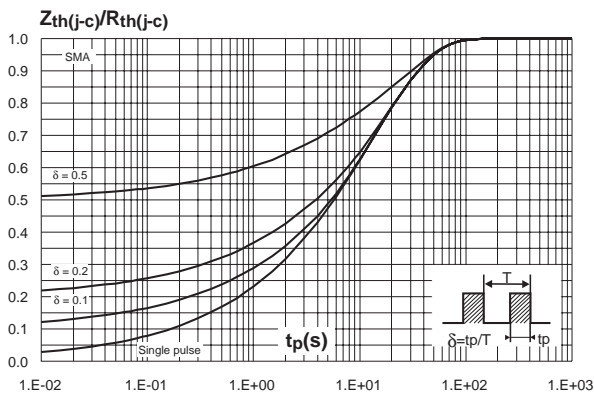


Fig. 6-2: Relative variation of thermal impedance junction to ambient versus pulse duration (DO-41).

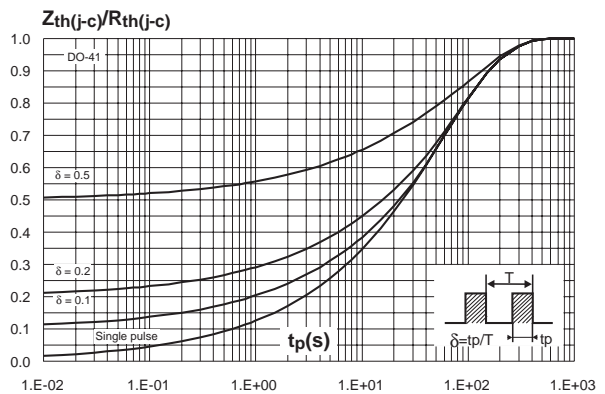


Fig. 7: Reverse leakage current versus reverse voltage applied (typical values).

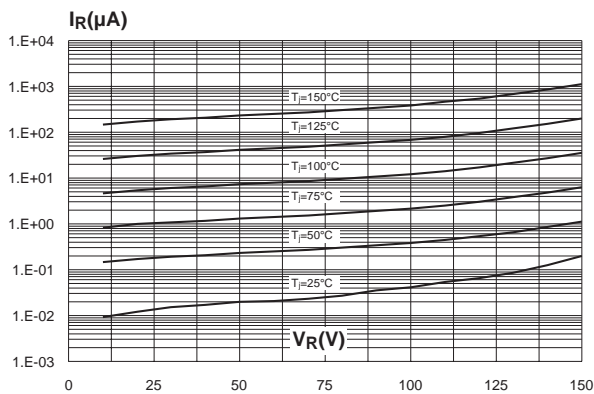


Fig. 8: Junction capacitance versus reverse voltage applied (typical values).

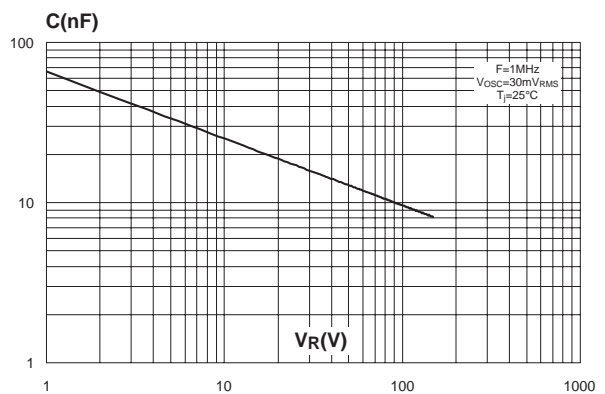


Fig. 9-1: Forward voltage drop versus forward current (low level).

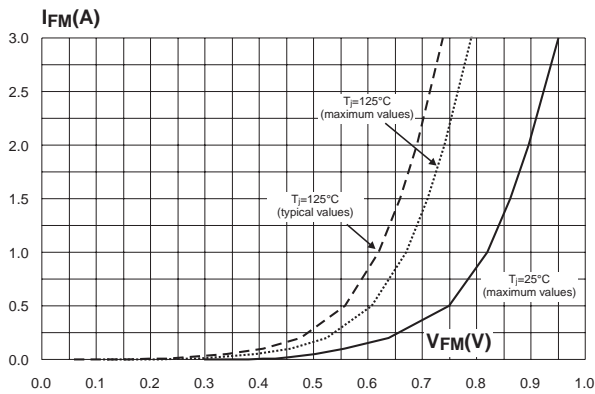


Fig. 9-2: Forward voltage drop versus forward current (high level).

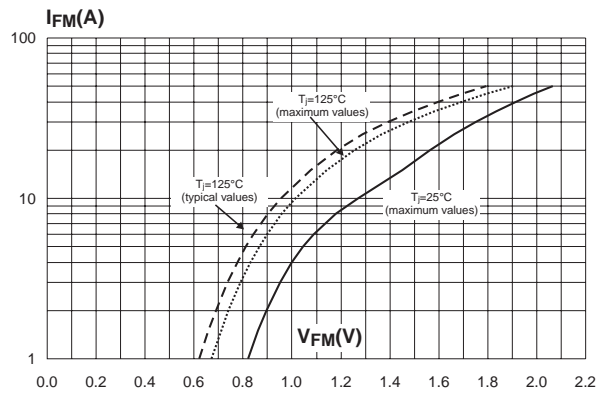


Fig. 10: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, Cu: 35µm) (SMA).

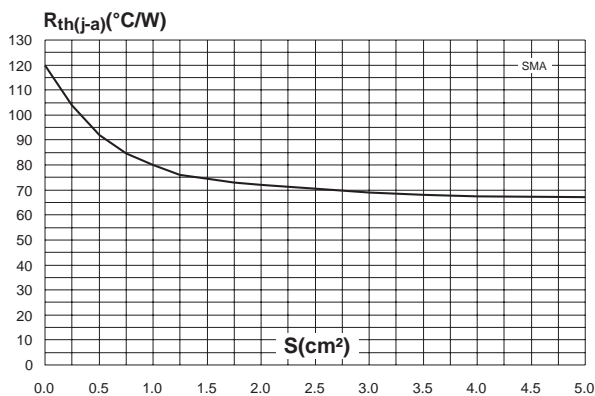
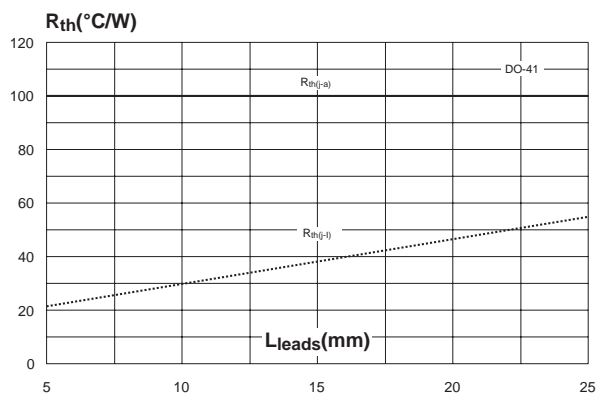
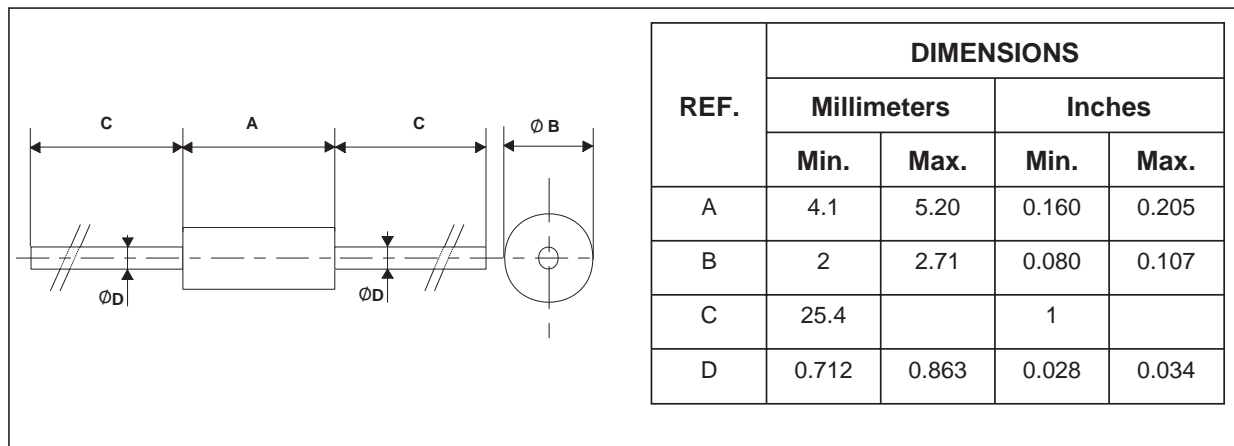


Fig. 11: Thermal resistance versus lead length (DO-15).

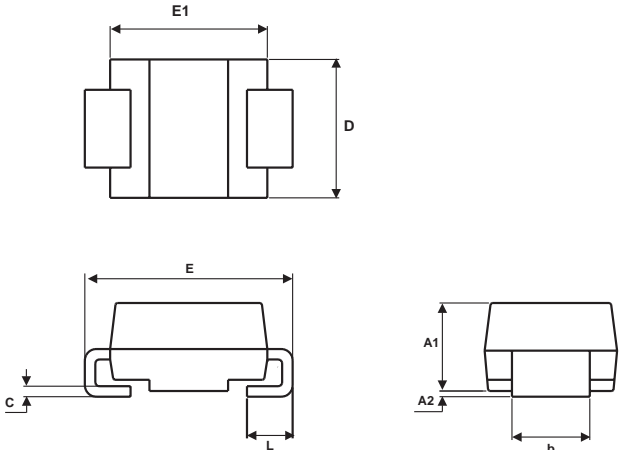
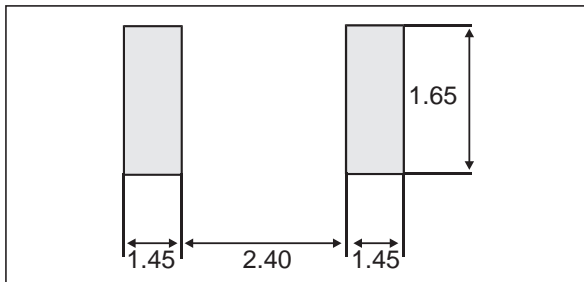


PACKAGE MECHANICAL DATA
DO-41 plastic



PACKAGE MECHANICAL DATA
SMA (JEDEC DO-214AC)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.70	0.075	0.106
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116
L	0.75	1.60	0.030	0.063


FOOT PRINT DIMENSIONS (in millimeters)


Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS1150	STPS1150	DO-41	0.34 g	2000	Ammopack
STPS1150RL	STPS1150	DO-41	0.34 g	5000	Tape & Reel
STPS1150A	1150	SMA	0.068 g	5000	Tape & Reel

- Epoxy meets UL94,V0

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